

Title (en)  
COOLING DEVICE

Title (de)  
KÜHLVORRICHTUNG

Title (fr)  
DISPOSITIF DE REFROIDISSEMENT

Publication  
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Application  
**EP 01956404 A 20010728**

Priority  
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Abstract (en)  
[origin: WO0215268A2] The invention relates to a cooling device for at least one semiconductor and/or at least one integrated electronic circuit that is linked with a thermoconducting element. Said cooling device comprises a heat sink that is linked with the thermoconducting element so as to conduct heat. Said thermoconducting element, on the side facing the heat sink, is provided with structures that enlarge its surface. The invention is further characterized in that the heat sink (W), on its side facing the thermoconducting element (7), is provided with counterstructures (10) that enlarge its surface and that engage with the structures (9).

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**H01L 23/40**

IPC 8 full level  
**H01L 23/40** (2006.01)

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**H01L 23/4006** (2013.01); **F28F 3/048** (2013.01); **F28F 3/12** (2013.01); **H01L 2224/48227** (2013.01)

Citation (search report)  
See references of WO 0215268A2

Citation (examination)  
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DOCDB simple family (publication)  
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